

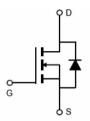
# MJ N-Channel Enhancement Mode Power MOSFET

### Description

The MJ6005AR uses advanced trench technology and design to provide excellent R DS(ON) with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

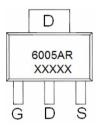
- ♦ V<sub>DS</sub> =60V,I<sub>D</sub> =5A R<sub>DS(ON</sub>) <35mΩ @ V<sub>GS</sub> =10V (Typ.26mΩ) R<sub>DS(ON</sub>) <45mΩ @ V<sub>GS</sub> =4.5V (Typ.32mΩ)
- $R_{DS(0N)} < 45m\Omega @ V_{GS} = 4.5V (Typ.32m\Omega)$  $\bullet$  High density cell design for ultra low Rdson
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  Fully characterized avalanche voltage and current
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  Good stability and uniformity with high E<sub>As</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability



Schematic diagram

# Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



SOT-223-3L view

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ6005AR	MJ6005AR	SOT-223-3L	Ø330mm	12mm	2500 units

#### Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ld	5	А
Drain Current-Continuous(Tc =100℃)	ID(100℃)	3.5	А
Pulsed Drain Current	ldм	24	А
Maximum Power Dissipation	PD	2	W
Operating Junction and Storage Temperature Range	Тј,Тѕтс	-55 To 150	°C

#### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	Røja	62.5	°C/W	
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# Electrical Characteristics (T<sub>A</sub> =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics	I	1	1		1	
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	60	-	-	V
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)		1	1	1	1	1
Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1.2	1.6	2.5	V
Desia Course On Otata Desistance		V <sub>GS</sub> =10V, I <sub>D</sub> =5A	-	26	35	mΩ
Drain-Source On-State Resistance	Rds(on)	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	32	45	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =5A	11	-	-	S
Dynamic Characteristics (Note 4)				1	1	1
Input Capacitance	Clss	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V, F=1.0MHz	_	979	_	PF
Output Capacitance	Coss		-	120	-	PF
Reverse Transfer Capacitance	Crss		-	100	-	PF
Switching Characteristics (Note 4)	I	1			1	
Turn-on Delay Time	td(on)		_	5.2	-	nS
Turn-on Rise Time	tr	VDD =30V,RL =6.7Ω	-	3	-	nS
Turn-Off Delay Time	td(off)	$V_{GS} = 30V, R_{C} = 0.7\Omega^{2}$ V <sub>GS</sub> = 10V, R <sub>G</sub> = 3Ω	-	17	-	nS
Turn-Off Fall Time	tr	_	-	2.5	-	nS
Total Gate Charge	Qg		-	22	-	nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =30V,I <sub>D</sub> =5A, V <sub>GS</sub> =10V	-	3.3	-	nC
Gate-Drain Charge	Qgd		-	5.2	-	nC
Drain-Source Diode Characteristics	I		<u> </u>	<u> </u>	<u> </u>	<u> </u>
Diode Forward Voltage (Note 3)	Vsd	V <sub>GS</sub> =0V,Is =5A	-	-	1.2	V
Diode Forward Current (Note 2)	ls		-	-	5	A
Forward Turn-On Time	ton	Intrinsic turn-on time is ne	aliaible (tr		  aminatad k	

#### Notes:

1 Repetitive Rating: Pulse width limited by maximum junction temperature.

② Surface Mounted on FR4 Board,  $t \le 10$  sec.

③ Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

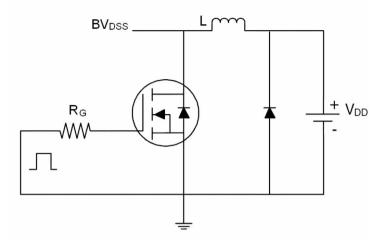
4 Guaranteed by design, not subject to production

5 EAS condition : Tj=25°C,V\_DD=30V,V\_G=10V,L=0.5mH,Rg=25\Omega

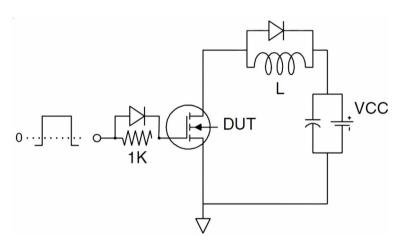




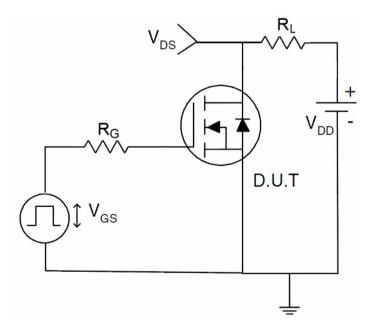
### Test Circuit





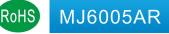


Gate charge test Circuit

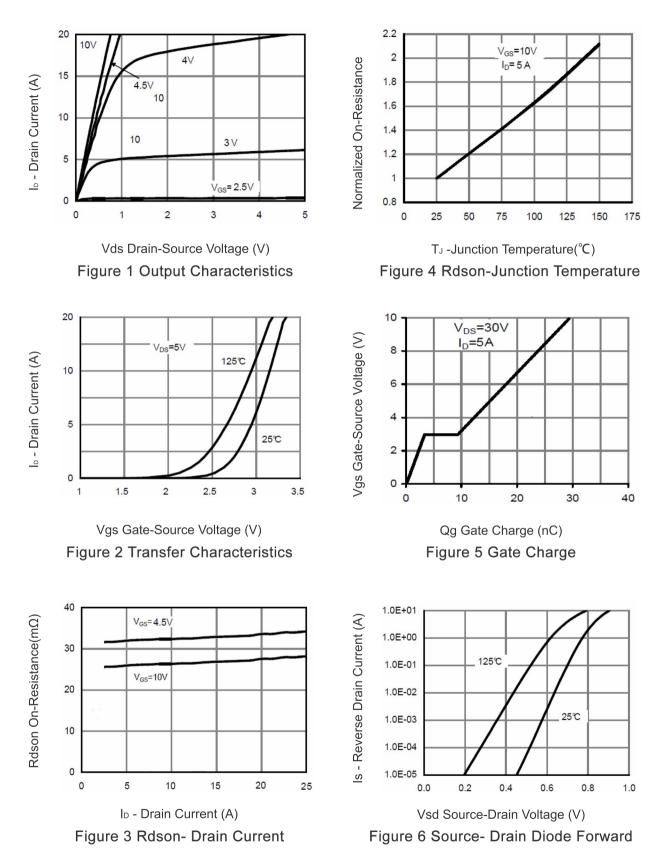


Switch Time Test Circuit





## Typical Electrical and Thermal Characteristics (Curves)









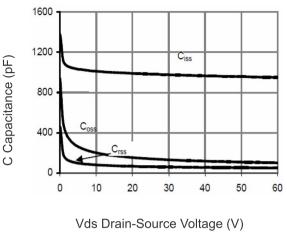
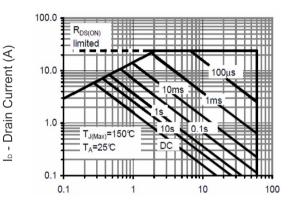
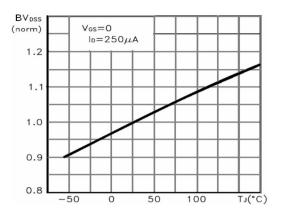


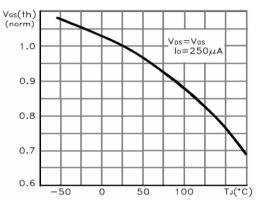
Figure 7 Capacitance vs Vds



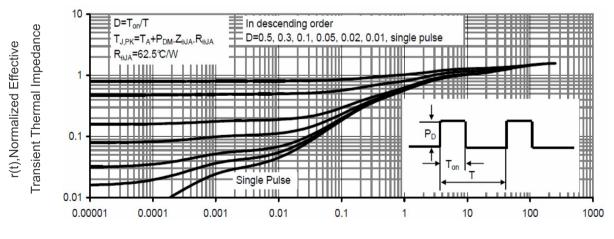
Vds Drain-Source Voltage (V) Figure 8 Safe Operation Area



TJ -Junction Temperature(℃) Figure 9 BVDss vs Junction Temperature



TJ -Junction Temperature(°C) Figure 10 VGs(th) vs Junction Temperature

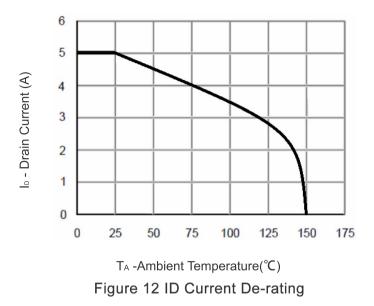


Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



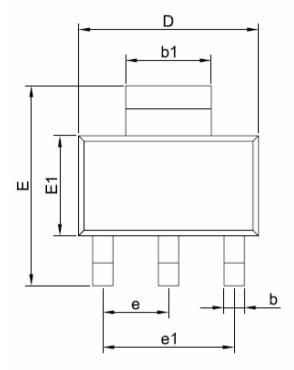




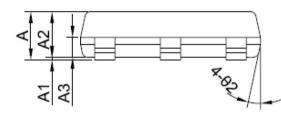












NOTES: DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS

SYMBOL	MIN	NOM	MAX	
A	1.55		1.80	
A1	0.02		0.12	
A2	1.45	1.60	1.75	
A3	0.60	0.70	0.80	
b	0.60		0.80	
b1	2.90		3.10	
С	0.24		0.32	
D	6.20	6.30	6.50	
E	6.70	7.00	7.30	
E1	3.30	3,50	3.70	
е	2.299REF			
e1	4.598REF			
L	0.90MIN			
L2	0.30BSC			
θ	0°		10°	
θ 1	10°	12°	14°	
θ <sub>2</sub>	10°	12°	14°	





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